

COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△					△				
△					△				
<b>APPLICABLE STANDARD</b>									
RATING	OPERATING TEMPERATURE RANGE	-35 °C TO +85 °C(NOTE1)			STORAGE TEMPERATURE RANGE	-10 °C TO +60 °C(NOTE3)			
	OPERATING MOISTURE RANGE	20 % TO 80 %(NOTE2)			STORAGE MOISTURE RANGE	40 % TO 70 %(NOTE3)			
	CURRENT	1 A			VOLTAGE	150 V AC(DC)			
<b>SPECIFICATIONS</b>									
ITEM		TEST METHOD			REQUIREMENTS			QT	AT
<b>CONSTRUCTION</b>									
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			ACCORDING TO DRAWING.			×	×
MARKING		CONFIRMED VISUALLY.						×	×
<b>ELECTRIC CHARACTERISTICS</b>									
CONTACT RESISTANCE		100 mA (DC OR 1000 Hz).			30 mΩ MAX.			×	—
CONTACT RESISTANCE-MILLIVOLT LEVEL METHOD.		20 mV MAX, 1mA(DC OR 1000 Hz)							
INSULATION RESISTANCE		100 V DC.			500 MΩ MIN.			×	—
VOLTAGE PROOF		500 V AC FOR 1 min.			NO FLASHOVER OR BREAKDOWN.			×	—
<b>MECHANICAL CHARACTERISTICS</b>									
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.			① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			×	—
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			① NO ELECTRICAL DISCONTINUITY OF 1 μs.			×	—
SHOCK		490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			×	—
<b>ENVIRONMENTAL CHARACTERISTICS</b>									
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 →-5 TO 35→+85 →5 TO 35°C TIME 30 →10 TO 15 →30 →10 TO 15min UNDER 5 CYCLES.			① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN.			×	—
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 ~ 95 %, 96 h.			③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				
RESISTANCE TO SOLDERING HEAT		(1) REFLOW SOLDERING «REFLOW AREA» MAX 250°C WITHIN 10 sec. MIN 220°C WITHIN 70 sec «PREHEATING AREA» 150°C to 160 °C 60 sec. To 120 sec. PUT THROUGH IN REFLOW FUMACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE 350±5°C, FOR 5±1 sec. NO STRENGTH ON CONTACT.			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			×	—
SOLDERABILITY		SOLDERING TEMPERATURE : 235±5°C DURATION OF IMMERSION : SOLDERING, FOR 3 sec.			A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.			×	—
REMARKS				DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED	
NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NON-CONDENSING NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.				<i>I. Donfouza</i>	<i>I. Donfouza</i>	<i>T. Miyajima</i>	<i>T. Miyajima</i>		
Unless otherwise specified, refer to JIS C 5402				03.03.05	03.03.05	03.03.05	03.03.05		
Note QT:Qualification Test AT:Assurance Test ×:Applicable Test									
<b>HRS</b> HIROSE ELECTRIC CO., LTD.				SPECIFICATION SHEET			PART NO. DF14H-20P-1.25H(56)		
CODE NO.(OLD)		DRAWING NO.		PART NO.				1	
CL		ELC4-161459-03		CL538-0167-0-56				1	

Apr.1.2017 Copyright 2017 HIROSE ELECTRIC CO., LTD. All Rights Reserved.

TO

